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By: Ruth Montalvo / Ruth Montalvo Date: 12/22/05

Customer No. 026418

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney's Docket No.: **JG-SU-5221/500577.20071**

U.S. Application No.:

International Application No.: **PCT/JP2004/015999**

International Filing Date: **OCTOBER 28, 2004** 28 OCTOBER 2004

Priority Date Claimed: **DECEMBER 10, 2003** 10 DECEMBER 2003

Title of Invention: **PROCESSING METHOD OF SILICON WAFER**

Applicant(s) for (DO/EO/US): **Sakae KOYATA and Kazushige TAKAISHI**

Mail Stop PCT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313 1450

PRELIMINARY AMENDMENT

Sir:

The above-identified application is filed concurrently herewith, please amend the specification as follows:

Amendments to the specification begin on page 2 of this paper.

Amendments to the Abstract begin on page 3 of this paper.

Remarks / Arguments begin on page 4 of this paper.